



FEATURES

- Magnetic designs to support every PHY
- Meet or exceed IEEE 802.3af and ANSI X3.263 standards
- Meet IEEE 802.3at standards
- including 350uH min OCL with 8mA bias
- Minimum 1500Vrms isolation per IEEE 802.3 requirement
- Designed for 100 base transmission over UTP-5 cable
- Size same as RJ-45 modular jack to save PCB board Space
- Recognized by UL 60950-1

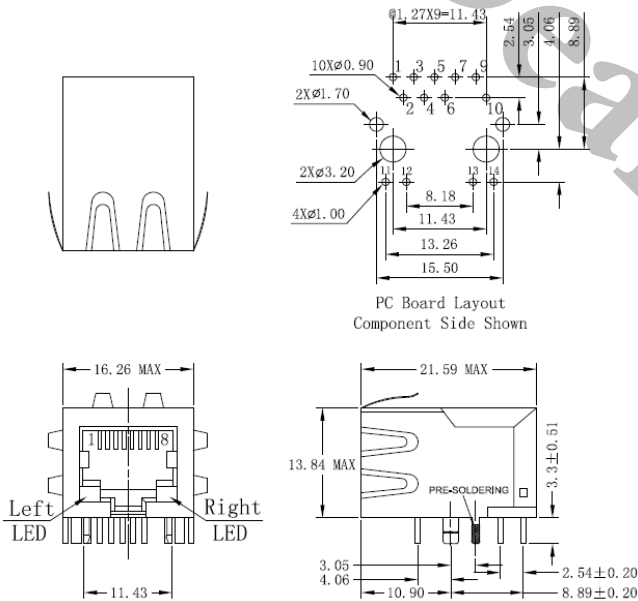


ELECTRICAL SPECIFICATIONS @25°C-Operating temperature 0°C TO 70°C

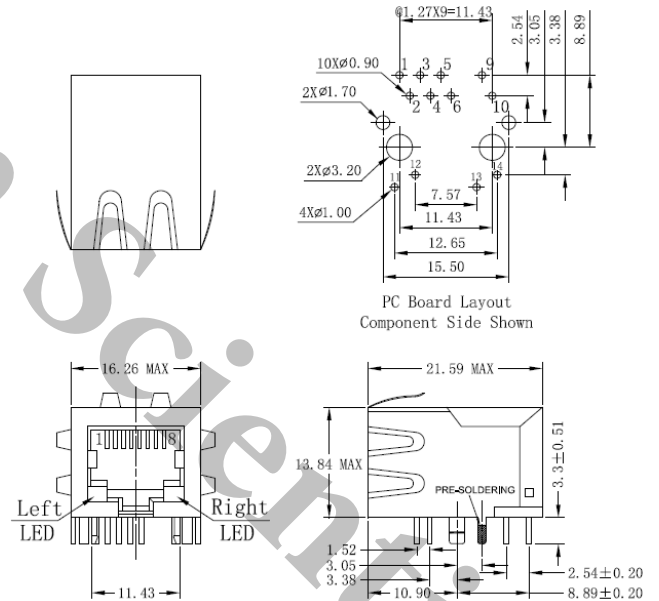
Part Number	Turns Ratio Pri:Sec. ±3%		EMI Fingers	LED (L/R)	Insertion Loss (dB max)	Return Loss (dB min @100 Ω)					Crosstalk (dB TYP.)	Common Mode Rejection (dB TYP.)			Hipot (V _{rms} min)
	TX	RX				0.3-100 MHz	0.5-30 MHz	40 MHz	50 MHz	60-80 MHz		0.3-100 MHz	30-60 MHz	60-100 MHz	
13F-67BYGDD2NL	1CT:1CT	1CT:1CT	YES	Y/G	-1.1	-18	-15.5	-13.6	-12	-38	-50	-40	-30	1500	
13F-67CGYDS2NL	1CT:1CT	1CT:1CT	YES	G/Y	-1.1	-18	-15.5	-13.6	-12	-38	-50	-40	-30	1500	

Mechanicals and Dimensions

13F-67B

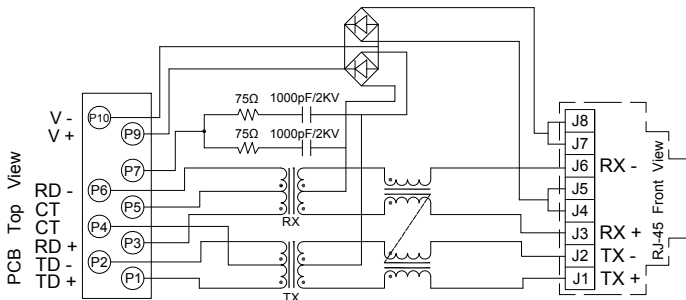


13F-67C

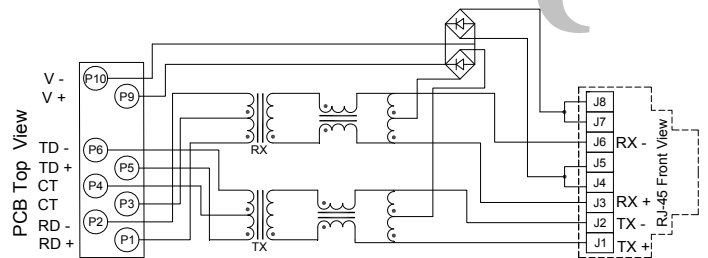


SCHEMATICS

13F-67B



13F-67C



MATERIALS

Part Number

1. Housing Material:

MATERIAL:NYLON GF (Fr50) UL94V-0 STANDARD COLOR:BLACK

2. Insert Material:

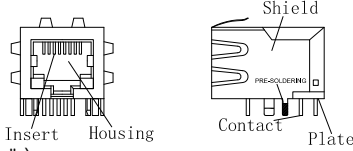
MATERIAL:Phos-Bronze C5210 EH--0.35mm Thickness

Insert -PBT GF UL94V-0

1.PLATING(1) NICKEL

2.PLATING(2) 100%Sn

3.PLATING(3) GOLD (3u " ~50u ")



13F - 67C GYDS NW 2 NL
A B C D E F

A:Series

B:Schematics

C:Led

D:Mechanical

E:Gold Plating:1=3u",2=6u",3=15u",4=30u",5=50u"

F:RoHS version

3. Plate Material: PBT GF UL 94V-0

4. Contact pin Material:

MATERIAL: Phos-Bronze C5191---0.35mm Thickness

1.PLATING(1) NICKEL

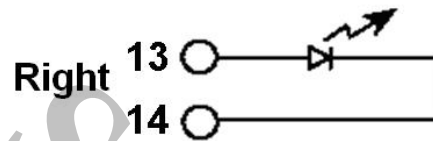
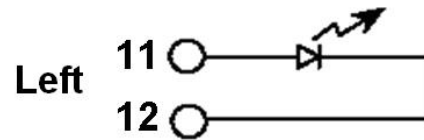
2.PLATING(2) 100%Sn

5. Shielding Material:RASS C2680 PLATING NICKEL

6. Operating Life:750 Cycles MIN.

7. MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68,SUBPART F.

LED Configuration



Vin=2.1Vdc TYP. 2.5Vdc MAX.

Standard LED	Wavelength	Forward* V(MAX)	(TYP)
Yellow	585 nm	2.5 V	2.1 V
Green	565 nm	2.5 V	2.2 V

* With a forward current of 20 mA